

VP-101MX-M/C 9 H VP-151MX-M/C 6 H

High Resolution Thermoelectric Peltier Cooled Camera



The VP-101MX and VP-151MX, the latest models of the industrial proven VP series, are equipped with the CoaXPress interface and based on the latest CMOS image sensor technology (IMX461 and IMX411) from Sony Semiconductor Solutions Corporation. The VP-101MX-9 offers up to 8.7 frames per second at 11648 \times 8742 resolution. For even higher resolution applications, the VP-151MX-6 offers up to 6.2 frames per second at 14192 \times 10640 resolution. These cameras use thermo-electric Peltier (TEC) cooling technology developed for and used by many demanding medical market customers. The TEC maintains the operating temperature of the CMOS image sensor at up to 15 degrees below ambient temperature. These cameras provide a stable operating condition and the ability to expose for a long period of time to increase camera sensitivity. Featured with the stable operating capability and high resolution, these cameras are ideal for demanding applications such as FPD, PCB and semiconductor inspections.

Pyramid Imaging Inc • 945 East 11th Avenue • Tampa, FL 33605 • +1 813 984 0125 • sales@pyramidimaging.com • pyramidimaging.com



Main Features

- Thermoelectric Peltier Cooled 15°C below
- 101 or 151 Megapixel Resolution
- CoaXPress Interface
- Electronic Rolling Shutter
- DSNU and PRNU Correction
- Flat Field Correction with Sequencer Control
- Hot Pixel Correction

Specifications

• Dynamic Defective Pixel Correction

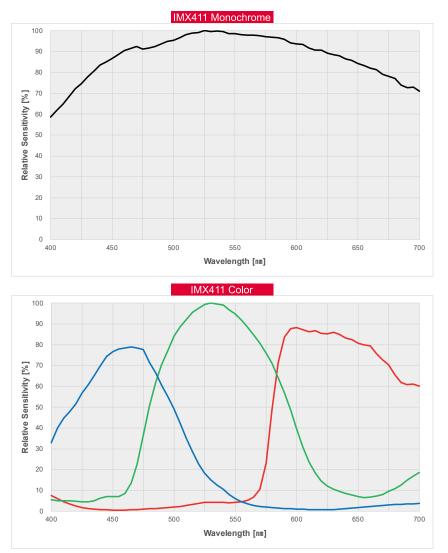
Applications

- Flat Panel Display Inspection
- Electronics Inspection
- Semiconductor Inspection
- Document / Film Scanning

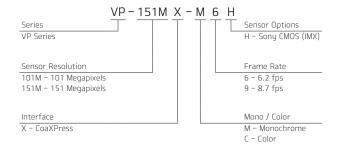
Model		VP-101MX-M/C 9 H	VP-151MX-M/C 6 H
Resolution (H $ imes$ V)		11648 × 8742	14192 × 10640
Sensor		SONY IMX461	SONY IMX411
Sensor Size (Diagonal)		43.80 mm \times 32.87 mm (55 mm)	53.36 mm $ imes$ 40.01 mm (66.7 mm)
Pixel Size		3.76 μ m $ imes$ 3.76 μ m	
Interface		CoaXPress (CXP-3 / CXP-6)	
Max. Frame Rate		8.7 fps (with Overlapped Acquisition)	6.2 fps (with Overlapped Acquisition)
Exposure Time (1 μ s step)		1 µs - 60 s	
Binning	Sensor	imes1, $ imes$ 3 (Horizontal and Vertical Dependent)	
	Logic	imes1, $ imes$ 2, $ imes$ 4 (Horizontal and Vertical Independent)	
Pixel Data Format		8 / 10 / 12 / 14 / 16 bit	
Electronic Shutter		Rolling Shutter	
Trigger Synchronization	Overlapped Acquisition	Free-Run	
	Non-overlapped Acquisition	Hardware Trigger, Software Trigger or CXP	
Dynamic Range		78 dB	
Gain Control		1×~32×	
Black Level Control		0 ~ 4095 LSB at 16 bit	
Cooling Method		Thermoelectric Peltier Cooling	
Cooling Performance		15℃ below ambient temperature – Standard cooling with a fan	
Dimension / Weight		100 mm $ imes$ 100 mm $ imes$ 88 mm, 1.1 kg (with M-72 mount)	110 mm $ imes$ 110 mm $ imes$ 85 mm, 1.4 kg (with M–72 mount)
Temperature		Operating: 0°C ~ 40°C, Storage: −40°C ~ 70°C	
Software Trigger		Asynchronous, Programmable via Camera API	
Lens Mount		M72-mount, Custom mount available upon request	
Power	External	11 ~ 24 V DC	
	Dissipation	Typ. 26.0 W	
Compliance		CE, FCC, KC	
API SDK		Vieworks Imaging Solution 7.X	

High Resolution Thermoelectric Peltier Cooled Camera

Relative Sensitivity Curves



Ordering Scheme



Connector Specification

Power



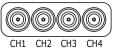
1, 2, 3: +12V DC 4, 5, 6: GND (HR10A-7R-6PB)

Control



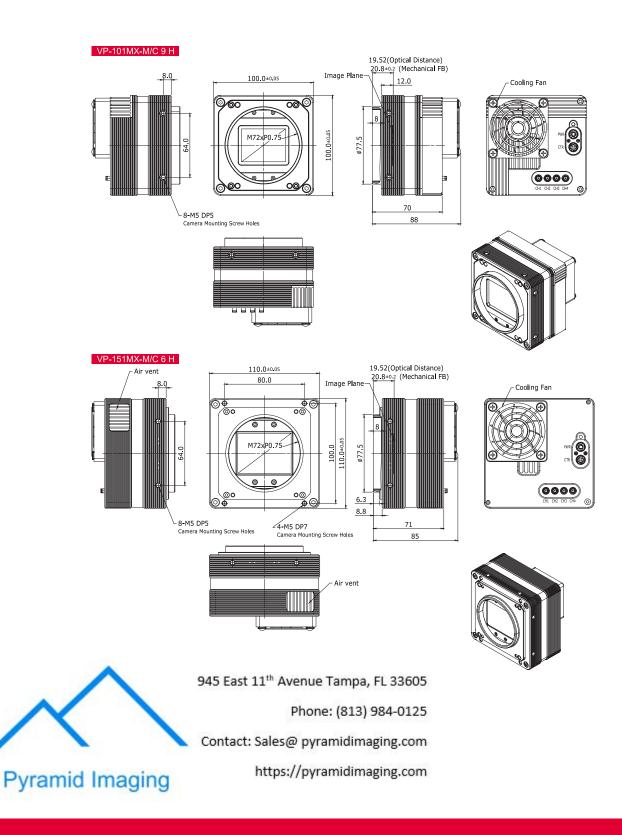
1: Trigger IN+ 2: Trigger IN-3: Strobe Out-(GND) 4: Strobe OUT+ (HR10A-7R-4S)

Data Transfer / Communications



CH1: Master Connection 75 $\ensuremath{\Omega}$, DIN 1.0/2.3

Mechanical Dimensions



41–3, Burim–ro 170 beon–gil, Dongan–gu, Anyang–si, Gyeonggi–do, 14055 Republic of Korea Tel +82–70–7011–6161 Fax +82–31–386–8631 E-mail vision@vieworks.com Web www.vieworks.com

Unit: mm

